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IKEDA et al.(10) **Pub. No.: US 2022/0369456 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **WIRING SUBSTRATE AND METHOD FOR
MANUFACTURING WIRING SUBSTRATE**(71) Applicant: **IBIDEN CO., LTD.**, Ogaki (JP)(72) Inventors: **Tomoyuki IKEDA**, Ogaki (JP);
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ABSTRACT

A wiring substrate includes a first insulating layer, a conductor layer formed on the first insulating layer, a second insulating layer formed on the first insulating layer such that the second insulating layer is covering the conductor layer, and a coating film formed on a surface of the conductor layer such that the coating film is adhering the conductor layer and the second insulating layer. The conductor layer includes a conductor pad and a wiring pattern, and the conductor pad of the conductor layer has a mounting surface including a first region and a component mounting region formed such that the second insulating layer has a through hole exposing the component mounting region and that the first region is covered by the second insulating layer and roughened to have a surface roughness higher than a first surface roughness of a surface of the wiring pattern facing the second insulating layer.

